Special Issue

Machine Vision and 3D Sensing in Smart Agriculture

Message from the Guest Editors

In recent decades, machine vision and 3D sensing technologies have enabled precision agriculture practices. This Special Issue focuses on agricultural problems, machine vision, and 3D sensing techniques applied to smart or precision agriculture for plant phenotyping, crop monitoring, stress detection, yield prediction, fruit or vegetable quality detection, etc. Traditional and advanced sensing technologies, including visible imaging, near-infrared image, multispectral imaging, hyperspectral imaging, remote sensing, structured light, laser radar, and binocular vision, are increasingly used for various agricultural applications. The Special Issue highlights these technologies for increasing agricultural productivity, reducing resource wastage, and mitigating environmental impacts. Overall, the Special Issue provides valuable insights into the current status and future directions of machine vision and 3D sensing in smart agriculture.

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Deadline for manuscript submissions

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Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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